

**FLYING PROBE SYSTEM** 

# Pilot<sup>4D</sup> V8

## Pilot<sup>4D</sup> Line



The Pilot<sup>4D</sup> V8 represents the latest frontier in flying probe test technology; it is the complete solution for those who want maximum performance: the highest test speed, low to medium volume, test coverage and flexibility, for prototyping, manufacturing, or repairing any type of board. Its vertical architecture is the optimum solution for probing both sides of the UUT simultaneously. This increases test throughput and flexibility while guaranteeing fast, precise, reliable and repeatable probing and full availability of all the mobile resources for testing the UUT. This solution represents an important technological innovation in double-sided flying probe test, overcoming the intrinsic limitations of horizontal systems. The Pilot<sup>4D</sup> V8 is equipped with 8 electrical flying test probes (4 on each side), 2 Openfix flying probes (1 on each side), 2 power flying probes (1 on each side) and 2 CCD cameras (1 on each side), for a total of 14 mobile resources available to test the UUT. The mobile power probes are another important innovation which enables power up of the UUT without requiring any additional fixed cables, allowing easy implementation of functional test.





#### The test tools and techniques of the PILOT<sup>4D</sup> V8 include:

- FNODE signature analysis on the nets of the UUT
- Standard analog and digital in-circuit test
- · Vectorless tests (JSCAN and OPENFIX), to test ICs for opens and shorts
- PWMON net analysis for power on the boards
- Continuity test to detect open tracks on the PCB
- Visual tests for component presence/absence and rotation
- Optional functional test and boundary scan test capabilities
- On Board Programming tools for digital devices
- Optional Thermal Scan Resources

All of these measurement capabilities and techniques can be combined in a single test program. Important innovations, such as the net-oriented, FNODE and PWMON measurement techniques, provide high fault coverage with significant savings in terms of programming and test time. In addition, with its full complement of test resources, **the Pilot**<sup>4D</sup> V8 can utilize the test programs developed on any other Seica flying probe system, since it has the capability to operate in all prober configurations (2 or 4 probes on a single side or on both sides).

#### VIP PLATFORM

The Pilot<sup>4D</sup> V8 is based on the Seica VIP platform, which includes the innovative VIVA software. Test program development is organized in 3 simple steps: "Prepare", "Verify" and "Test", where the user is guided through a series of automated operations in an intuitive, self-explanatory environment, drastically reducing programming time and minimizing errors and omissions, ensuring the quality of the final test program. For special applications, the extremely **open architecture of the VIP platform** enables easy integration of external software modules and/or hardware, such as via RS232, USB ports, GPIB and PXI/VXI protocols.

#### **TECHNICAL TABLE**

#### SEICA WORLDWIDE

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**SEICA SpA** via Kennedy 24 10019 Strambino - TO ITALY Tel: +39 0125 6368.11 Fax: +39 0125 6368.99 Email: sales@seica.com

#### PROXIMA S.r.I.

via Gorra, 55B 29122 Piacenza ITALY Tel: +39 0523 71 15 35 Fax: +39 0523 71 16 68 Email: info@proxima-ate.com

**SEICA Inc.** 50A Northwestern Drive Suite 10 - Salem NH 03079 - USA Tel: +1 603-890-6002-76-78 Fax: +1 603-890-6003 Email: sigillo@seica.com

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SEICA FRANCE SARL 30, Avenue Robert Surcouf 78960 Voisins Le Bretonneux FRANCE Tel.: +33 1 39 30 66 77 Fax: +33 1 39 30 66 78 Email: dupoux@seica.com



SEICA DEUTSCHLAND GmbH Am Postanger 18 83671 - Benediktbeuern GERMANY Tel.: +49 8857 6976742 Fax: +49 8857 6976745 Email: hauptmann@seica.com



SEICA ELECTRONICS (Suzhou) Co.Ltd. XingHan Street Suzhou Industrial Park, Jiangsu Province, 215021 CHINA Tel.: +86 512 67610421 Fax: +86 512 67610423 Email: seicachina@seica.com

Seica reserves the right to change the technical specifications without notice



PROBES AND CAMERAS			
Probes Position - Test Side		Front/Rear	
Maximum Number of Resources		14	
Number of Electrical Probes		8 (4 front, 4 rear)	
Number of Openfix Probe	÷S	2 (1 front, 1 rear)	
Number of Power Probes		2 (1 front, 1 rear)	
Number of Fixed Probes	/ Upgrade Up To	0/192	
Number of CCD Compress	led Channels	$\frac{4}{2(1 \text{ front } 1 \text{ roor})}$	
Automatic Marker Becon	nition	Ves	
Automatic UUT Planarity Compensation		Yes	
Thermal Scan Module (or	otion)	2 (1 front, 1 rear)	
	,	· · · ·	
BOARD CLAMPING SYST	EM, UUT SIZES AND WO	ORK AREA (*)	
Board Clamping System		Manual (Dual Action)	
Active lest Area		538 x 610 mm (21.18 X 24") Manual	
Poord Size		520 X 610 mm (20.47 X 24") Auto	
Board Size		518 x 610 mm (20 39 X 24")	
Minimum Board Size (*)		30 x 20 mm (0 78 x 0 78")	
Maximum Board Thickne	ss	5 mm (0.19") manual/3mm(0.18") aut	tomatic
Minimum Board Thicknes	SS SS	0.3 mm (0.00118")manual/1mm (0.003	93")auto
Maximum Component He	eight	37 mm (1.456")auto	
Board Loading		Vertical	
UUT Fly Height Clearance	e	Front (mm) Back (mm)	
4 x 4		40 40	
4 X 2		40 90	
4 X U 2 X 2		40 <u>300</u> 90 90	-
2 x 4		90 40	
0 x 4		300 40	
UUT Edge Clearance		2 mm manual/6 mm auto	
PITCH		000 (0 II)	
Minimum Pad Pitch		$200 \mu\text{m} (8 \text{mll})$	
Willing Pau Size	10 00	<i>ν</i> σ μπ (σ mm)	
PROBE FEATURES			
Z-axis Travel		-3.0 mm to 40 mm programmable	
Contact Force	10 11	25 g – 100 g programmable	
TESTS AND MEASUREM	ENTS (INSTRUMENTS D	SP)	
Voltage Generator 1 DC//		$\pm 1 \text{ mV to } \pm 10 \text{ V} (\pm 0.1\%)$	
Voltage Generator 3 DC/AC (DRC)		$\pm 1 \text{ mV to } \pm 10 \text{ V} (\pm 0.1\%)$	
Current Generator DC/AC		$\pm 25$ mV to $\pm 100$ V ( $\pm 0.2$ %) $\pm 1$ nA to $\pm 0.5$ A ( $\pm 0.1$ %)	
Waveform Generator 1 Sin, Tri, Arbitrary (DRA)		$1 \text{ Hz to } 3 \text{ MHz } (\pm 1 \text{ mHz}) - \pm 10 \text{ V m}$	nax
Waveform Generator 2 Si	n, Tri, Arbitrary (DRC)	1 Hz to 10 KHz (±10 mHz) - ±100	Vmax
Voltage Measurements D	C/AC	±200 µV to ±100 V	
Current Measurements D	C/AC	±3 nA to ±0.5 A	
Frequency Measurement	11	0.1 Hz to 10 MHz	
Digital Embedded Chann	el	±12 V - 500 mA - 10 MHz	
Resistance Measurement		1 mΩ to 100 MΩ	
Lapacitance measurement			
Zener Measurement	10 11 11	$\mu$	
Automatic Visual Inspect	ion	Yes	
<b>GENERAL REQUIREMEN</b>	TS		
Temperature Range		$25^{\circ}C \pm 10^{\circ}C$	
Humidity	A CONTRACTOR OF	30 - 80 %	
-	System	Loader	
Power	220 V/50 Hz 12 A,	220 V/50 Hz 2 A	
Power Consumption	110 V/60 HZ 24 A	1.0 kW max	
Air Flow	0.35 CEM - 101/min	0.3  CFM - 6l/min	
Weight	1800 kg (3699 lbs)	200 Kg (441 lbs)	
Longth	175 cm (68.9")	206 cm (81.10")	
Lengin	123 cm (48.4")	155 cm (61,02")	
Width	174 cm (68.50 <sup>°</sup> ")	174 cm (68.50") (214 cm with ligh	t-tower
Width Height		and the second se	
Width Height			
Width Height SOFTWARE FEATURES		Windows XP Windows 7	
Width Height SOFTWARE FEATURES PC/Operating System		Windows XP, Windows 7	
Width Height SOFTWARE FEATURES PC/Operating System Software Automatic Test Generatic	n	Windows XP, Windows 7 VIVA Ves	
Width Height SOFTWARE FEATURES PC/Operating System Software Automatic Test Generatic Autodebug	n	Windows XP, Windows 7 VIVA Yes Yes	
Width Height SOFTWARE FEATURES PC/Operating System Software Automatic Test Generatic Autodebug Data Input Format	n	Windows XP, Windows 7 VIVA Yes Yes CAD Data/Manual	

<sup>t</sup>Universal carrier for unique board configurations.